

Literature and Publications

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- K. Upadhyayula, "Why Test for Reliability?" Cascade Engineering Services, Redmond April 2008.
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- K. Upadhyayula, "Physics of Failure Approach to Product Reliability Workshop", Cascade Engineering Services, Redmond Jan 2008.
- K. Upadhyayula and A. Dasgupta, "A Physics-of-Failure Example of Acceleration Factor Assessment for Accelerated Qualification of Electronic Systems", Proceedings of Accelerated Stress Testing Workshop, IEEE CPMT, Pasadena, California, 1998.
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